

# **REGULATORY COMPLIANCE**











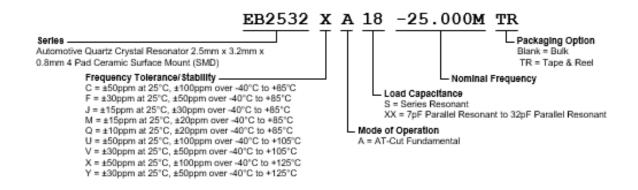
### **ITEM DESCRIPTION**

Automotive Grade Quartz Crystal Resonator 2.5mm x 3.2mm x 0.8mm 4 Pad Ceramic Surface Mount (SMD)

ELECTRICAL SPECIFICATIONS		
Nominal Frequency	8MHz to 66MHz	
Frequency Tolerance/Stability	±50ppm at 25°C, ±100ppm over -40°C to +85°C  ±30ppm at 25°C, ±50ppm over -40°C to +85°C  ±15ppm at 25°C, ±30ppm over -40°C to +85°C  ±15ppm at 25°C, ±20ppm over -40°C to +85°C  ±10ppm at 25°C, ±20ppm over -40°C to +85°C  ±50ppm at 25°C, ±100ppm over -40°C to +105°C  ±30ppm at 25°C, ±50ppm over -40°C to +105°C  ±50ppm at 25°C, ±50ppm over -40°C to +125°C  ±30ppm at 25°C, ±50ppm over -40°C to +125°C	
Aging at 25°C	±3ppm/year Maximum	
Load Capacitance	Series Resonant, 7pF Parallel Resonant to 32pF Parallel Resonant	
Shunt Capacitance	3pF Maximum	
Equivalent Series Resistance	800 Ohms Maximum over Nominal Frequency of 8MHz to 9.999999MHz 250 Ohms Maximum over Nominal Frequency of 10MHz to 10.999999MHz 150 Ohms Maximum over Nominal Frequency of 11MHz to 11.999999MHz 100 Ohms Maximum over Nominal Frequency of 12MHz to 12.999999MHz 80 Ohms Maximum over Nominal Frequency of 13MHz to 15.999999MHz 70 Ohms Maximum over Nominal Frequency of 16MHz to 20.999999MHz 60 Ohms Maximum over Nominal Frequency of 21MHz to 29.999999MHz 50 Ohms Maximum over Nominal Frequency of 30MHz to 66MHz	
Mode of Operation	AT-Cut Fundamental	
Drive Level	200μWatts Maximum	
Crystal Cut	AT-Cut	
Spurious Response	Measured from Fo to Fo +5000ppm -3dB Minimum	
Storage Temperature Range	-50°C to +150°C	
Insulation Resistance	Measured at 100Vdc 500 Megaohms Minimum	



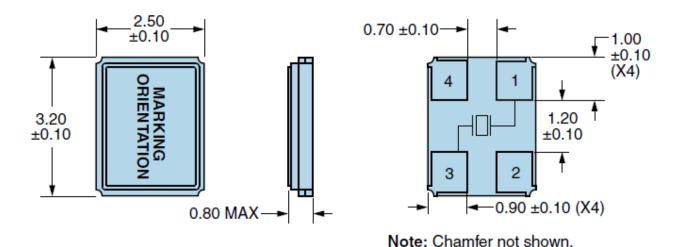
#### **PART NUMBERING GUIDE**



ENVIRONMENTAL & MECHANICAL SPECIFICATIONS		
ESD Susceptibility	MIL-STD-883, Method 3015, Class 1, HBM: 1500V	
Fine Leak Test	MIL-STD-883, Method 1014, Condition A	
Flammability	UL94-V0	
Gross Leak Test	MIL-STD-883, Method 1014, Condition C	
Mechanical Shock	MIL-STD-883, Method 2002, Condition B	
Moisture Resistance	MIL-STD-883, Method 1004	
Moisture Sensitivity	J-STD-020, MSL 1	
Resistance to Soldering Heat	MIL-STD-202, Method 210, Condition K	
Resistance to Solvents	MIL-STD-202, Method 215	
Solderability	MIL-STD-883, Method 2003	
Temperature Cycling	MIL-STD-883, Method 1010, Condition B	
Vibration	MIL-STD-883, Method 2007, Condition A	



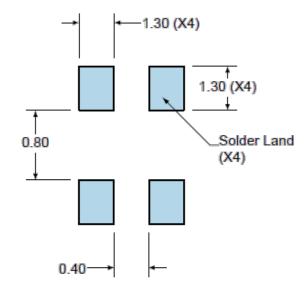
#### **MECHANICAL DIMENSIONS**



Seam Sealed

Terminal Plating Thickness: Gold (0.3 to 1.0μm) over Nickel (1.27 to 8.89μm).

### SUGGESTED SOLDER PAD LAYOUT



PIN	CONNECTION
1	Crystal
2	Cover/Ground
3	Crystal
4	Cover/Ground

All Tolerances are ±0.1

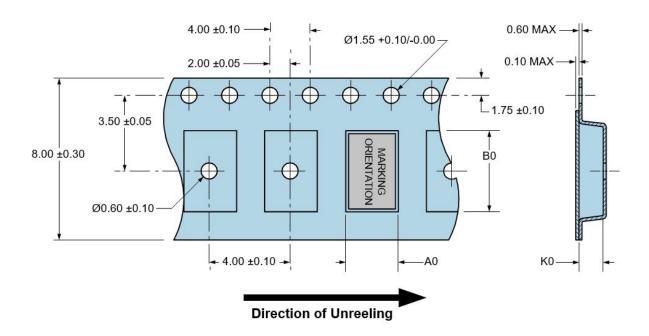
### **All Dimensions in Millimeters**

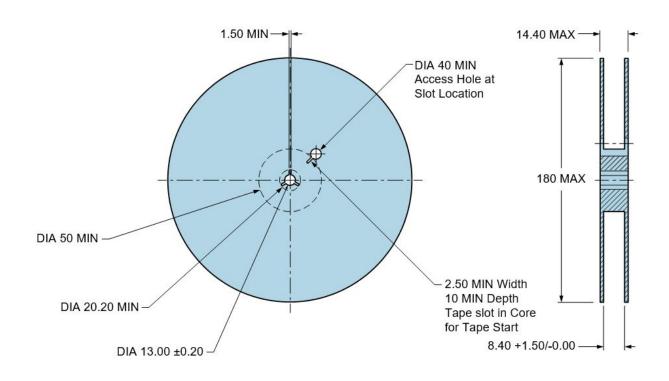


#### **TAPE & REEL DIMENSIONS**

Quantity per Reel: 3,000 Units

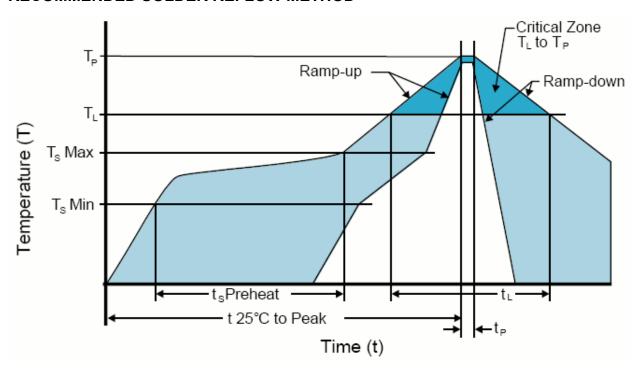
All Dimensions in Millimeters
Compliant to EIA-481







# **RECOMMENDED SOLDER REFLOW METHOD**



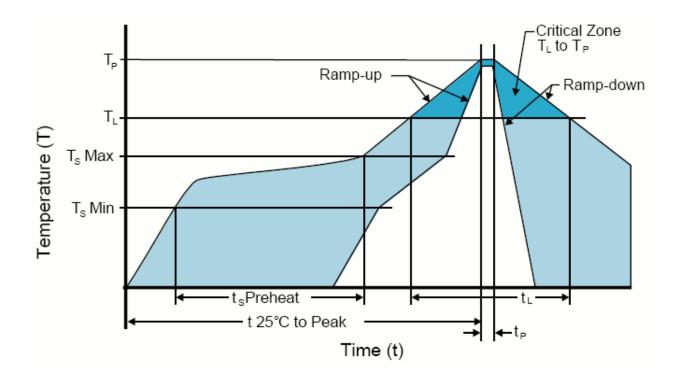
HIGH TEMPERATURE INFRARED/CONVECTION		
T <sub>s</sub> MAX to T <sub>L</sub> (Ramp-up Rate)	3°C/Second Maximum	
Preheat		
- Temperature Minimum (T <sub>s</sub> MIN)	150°C	
- Temperature Typical (T <sub>s</sub> TYP)	175°C	
- Temperature Maximum(T <sub>s</sub> MAX)	200°C	
- Time (t <sub>s</sub> MIN)	60 - 180 Seconds	
Ramp-up Rate (T <sub>L</sub> to T <sub>P</sub> )	3°C/Second Maximum	
Time Maintained Above:		
- Temperature (T <sub>L</sub> )	217°C	
- Time (t <sub>L</sub> )	60 - 150 Seconds	
Peak Temperature (T <sub>P</sub> )	260°C Maximum for 10 Seconds Maximum	
Target Peak Temperature(T <sub>P</sub> Target)	250°C +0/-5°C	
Time within 5°C of actual peak (tp)	20 - 40 Seconds	
Ramp-down Rate	6°C/Second Maximum	
Time 25°C to Peak Temperature (t)	8 Minutes Maximum	
Moisture Sensitivity Level	Level 1	
Additional Notes	Temperatures shown are applied to body of device.	

### **High Temperature Manual Soldering**

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)



# **RECOMMENDED SOLDER REFLOW METHOD**



LOW TEMPERATURE INFRARED/CONVECTION		
T <sub>s</sub> MAX to T <sub>L</sub> (Ramp-up Rate)	5°C/Second Maximum	
Preheat		
- Temperature Minimum (T <sub>S</sub> MIN)	N/A	
- Temperature Typical (T <sub>s</sub> TYP)	150°C	
- Temperature Maximum(T <sub>s</sub> MAX)	N/A	
- Time (t <sub>s</sub> MIN)	30 - 60 Seconds	
Ramp-up Rate (T <sub>L</sub> to T <sub>P</sub> )	5°C/Second Maximum	
Time Maintained Above:		
- Temperature (T <sub>L</sub> )	150°C	
- Time (t <sub>L</sub> )	200 Seconds Maximum	
Peak Temperature (T <sub>P</sub> )	245°C Maximum	
Target Peak Temperature(T <sub>P</sub> Target)	245°C Maximum 2 Times/230°C Maximum 1Time	
Time within 5°C of actual peak (t <sub>P</sub> )	10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time	
Ramp-down Rate	5°C/Second Maximum	
Time 25°C to Peak Temperature (t)	N/A	
Moisture Sensitivity Level	Level 1	
Additional Notes	Temperatures shown are applied to body of device.	

### **Low Temperature Manual Soldering**

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)

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